12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130107006
Qualification of Aizu as additional Fab site option for select devices in the CMOS7 process
Change Notification / Sample Request

Date: 1/28/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130107006
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LP5521TM/NOPB	LP5521TM NOPB
LP5521TM/NOPB	
LP5521TM/NOPB	LP5521TM/NOPB

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130107006	**PCN Date:**	01/28/2013

Title:	Qualification of Aizu as an additional Fab Site for select devices in CMOS7 process

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

***Proposed 1st Ship Date:**	04/28/2013	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

This change notification is to announce the addition of Aizu as a Fab site option for select devices in the CMOS7 Fab Process.

Current Site/Process/Wafer Diameter	**Additional Site/Process/Wafer Diameter**
MAINEFAB/CMOS7/200mm	**AIZU/CMOS7/200mm**

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Shipment Labels:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
MAINEFAB	CUA	USA

New

Chip Site	**Chip site code (20L)**	**Chip country code (21L)**
AIZU	**CU2**	**JPN**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
G4
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:		
LP5521TM/NOPB	LP5521TMX/NOPB	LP5521TMX/S7002954

Reference Qualification Data: CMOS7 Process at AIZU

Qualification Data: (Approved 12/17/2012)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device: LP5521TM_TL (MSL LEVEL1-260C)

Package Construction Details

Wafer Fab Site:	AIZU	Wafer Fab Process:	CMOS7 5V
Wafer Diameter:	200mm	Metallization:	Al .5%Cu
Passivation:	PECVDOX/NITRIDE		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail Lot#1	 Lot#2	 Lot#3
**Biased HAST	110C/85%RH (264 Hrs)	$76^{1}/0$	$72^{1}/0$	$73^{1}/0$
**Autoclave 121C	121C (96 Hrs)	77/0	77/0	77/0
**High Temp Storage Bake	150C (1000 Hrs)	77/0	-	-
ESD HBM	2000V	3/0	3/0	-
ESD CDM	500V	3/0	3/0	3/0
Latch-up	(per JESD78)	12/0	12/0	12/0
Power Cycle for Eprom	125C (10,000 Cyc)	77/0	77/0	77/0
High Temperature Data Retention	250C (82 Hrs)	77/0	77/0	77/0
Life Test	125C (1000 Hrs)	77/0	77/0	$76^{2}/0$
Temp Cycle	-40/125C (1068 Cyc)	$74^{3}/0$	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	Pass	Pass
**Preconditioning: MSL1@260C				

Note 1: Sample size reduced due to non-valid failures, not related to process qualification
Note 2: Unit lost
Note 3: Solder joint fatigue failures occurred after 500 cycles, not related to process qualification

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com